

Title (en)

METHOD FOR PRODUCTION OF THREE-Dimensionally ARRANGED CONDUCTING AND CONNECTING STRUCTURES FOR VOLUMETRIC AND ENERGY FLOWS

Title (de)

VERFAHREN ZUR HERSTELLUNG DREIDIMENSIONAL ANGEORDNETER LEIT- UND VERBINDUNGSSTRUKTUREN FÜR VOLUMEN- UND ENERGIESTRÖME

Title (fr)

PROCEDE DE FABRICATION DE STRUCTURES CONDUCTRICES ET DE LIAISON DISPOSEES DE MANIERE TRIDIMENSIONNELLE, DESTINEES A DES FLUX VOLUMIQUES ET ENERGETIQUES

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Application

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Abstract (en)

[origin: WO0150198A2] The invention relates to a method for production of three-dimensionally arranged conducting and connecting structures for volumetric and energy flows. Various light-setting materials are used for the production of the layers. Upon exchanging the materials, those layer regions in which no setting occurred during the preceding setting process, are also filled with new material, such that, in the subsequent setting process, not only is the upper layer linked to the one lying directly beneath it, but also material of the upper layer is connected to the material of a layer lying below the penultimate layer. It is thus possible, within the layer sequence, to connect a structure with varying properties from layer to layer.

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IPC 8 full level

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